

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L2	0	nuri-h\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:25	
2	BRS	L3	0	weselak-b\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:25	
3	BRS	L1	1	skocypec-r\$.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:26	
4	BRS	L4	16616 2	(clean or cleaning or cleaned or cleaner or cleanse or cleansing or cleansed or cleanser or treat or treating or treated or treatment or scrub or scrubbing or scrubbed or scrubber) adj10 (wafer or semiconductor or silicon or substrate or workpiece)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:27	
5	BRS	L5	57	(brush) adj10 (core) adj10 (fluid or liquid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:35	
6	BRS	L6	16722 1	(134/\$ or 15/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:27	
7	BRS	L7	8	14 same 15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:27	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
8	BRS	L8	2418	(brush) same (core) same (fluid or liquid or solution)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:36	
9	BRS	L9	2564	(15/77 or 15/88.2 or 15/88.3 or 15/102).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:45	
10	BRS	L10	4931	19 or 18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:45	
11	BRS	L11	51	19 and 18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB; USOCR	2004/08/30 13:45	